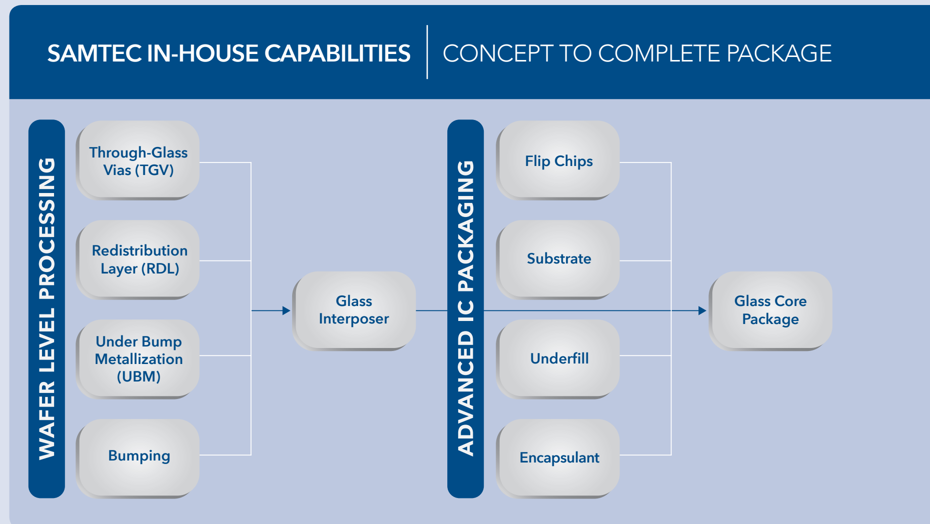
SAMTEC GLASS CORE TECHNOLOGY

THE NEXT GENERATION OF IC PACKAGING

Samtec is uniquely positioned to develop innovative products and technologies to support the ever increasing market demands for faster, smaller and less expensive devices.

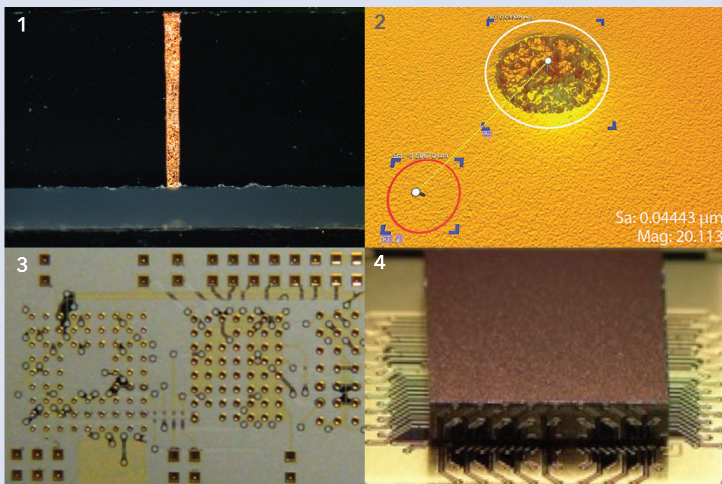
With these expanding requirements in mind, Samtec is investing in products and technologies that will support next generation systems, including a new proprietary Glass Core Technology that leverages the superior performance and material characteristics of glass to achieve significant miniaturization and integration possibilities.

The addition of this new technology, along with Samtec's advanced IC packaging capabilities, enables Samtec to provide unprecedented design, development and fabrication support for next generation systems.



DESIGN SPECIFICATIONS

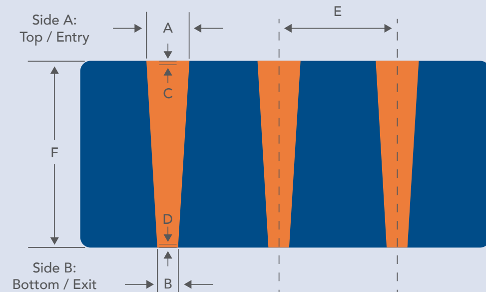
The challenges of generating small diameter through-holes in glass with fine pitches are eliminated with Samtec's proprietary Glass Core Technology which enables high-reliability IC packaging solutions with faster cycle times, KGD testing at higher packaging integration levels, and at the lowest cost in the marketplace.



1) Cu Filled Vias, 2) Metal to Glass Co-Planarity Sample, 3) RDL (Circuits on Glass), 4) Glass Core Packaging

FEATURE	DESCRIPTION	TYP (µm)	TOL (µm)
A*	Via Diameter Side A (µm)	40	± 2
B*	Via Diameter Side B (µm)	35	± 2
C	Metal to Glass Co-Planarity Side A (µm)	0	- 2
D	Metal to Glass Co-Planarity Side B (µm)	0	- 2
E*	Min Via Pitch (µm)	2x (A)	
F	Min Wafer Thickness (µm)	300	± 25

* Features A, B and E refer only to 300 µm thick wafers



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MICROELECTRONICS

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